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2013年12月

FCH76N60N

N 沟道 SupreMOS[®] MOSFET 600 V, 76 A, 36 mΩ

特性

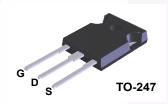
- $R_{DS(on)}$ = 28 m Ω (Typ.)@ V_{GS} = 10 V, I_D = 38 A
- 超低栅极电荷 (典型值 Q_q = 218 nC)
- 低有效输出电容 (典型值 Coss(eff.)= 914 pF)
- 100% 经过雪崩测试
- 符合 RoHS 标准

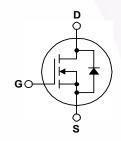
应用

- 太阳能逆变器
- · AC-DC 电源

说明

SupreMOS[®] MOSFET 是飞兆半导体的下一代高压超级结(SJ)技术,该技术采用区别于传统 SJ MOSFET 产品的深沟槽填充工艺。这项先进技术和精密的工艺控制提供了最低的 Rsp onresistance(导通电阻规格),卓越的开关性能和耐用性。SupreMOS MOSFET 技术适用于高频开关电源转换器应用,如功率因数校正 (PFC)、服务器/电信电源、平板电视电源、ATX电源及工业电源应用。





MOSFET 最大额定值 T_C = 25℃ 除非另有说明。

符号		参数		FCH76N60N	单位
V_{DSS}	漏极一源极电压			600	V
V_{GSS}	栅极一源极电压			±30	V
	温机中 达	- 连续 (T _C = 25°C)		76	А
ID	漏极电流	- 连续 (T _C = 100°C)		48.1	^
I _{DM}	漏极电流	- 脉冲	(注1)	228	Α
E _{AS}	单脉冲雪崩能量		(注2)	8022	mJ
I _{AR}	雪崩电流		(注1)	25.3	Α
E _{AR}	重复雪崩能量		(注1)	5.43	mJ
dv/dt	MOSFET dv/dt			100	V/ns
uv/ut	二极管恢复 dv/dt 峰值		(注3)	20	V/115
D	T+±1	(T _C = 25°C)		543	W
P_{D}	功耗	- 降低至 25°C 以上		4.34	W/°C
T _J , T _{STG}	工作和存储温度范围			-55 至 +150	°C
T_L	用于焊接的最大引脚温度	,距离外壳 1/8",持续 5 秒		300	°C

^{*} 漏极电流受限于最大结温

热性能

符号	参数	FCH76N60N	单位
$R_{\theta JC}$	结至外壳热阻最大值	0.23	°C/W
$R_{\theta JA}$	结至环境热阻最大值	40	30/00

封装标识与定购信息

器件编号	顶标	封装	包装方法	卷尺寸	带宽	数量
FCH76N60N	FCH76N60N	TO-247	塑料管	不适用	不适用	30 单元

电气特性 T_C = 25°C 除非另有说明。

符号	参数	测试条件	最小值	典型值	最大值	単位
关断特性						
BV _{DSS}	漏极一源极击穿电压	$I_D = 250 \mu A, V_{GS} = 0 V, T_C = 25^{\circ}C$	600	-	-	V
ΔBV _{DSS} / ΔT _J	击穿电压温度系数	I _D = 250 μA,参考 25°C	-	0.73	-	V/°C
	泰州共中区是共中 次	V _{DS} = 480 V, V _{GS} = 0 V	-	-	10	μΑ
DSS	零栅极电压漏极电流	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	100	μΑ
I _{GSS}	栅极 - 体漏电流	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

导通特性

$V_{GS(th)}$	栅极阈值电压	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	2.0	-	4.0	V
R _{DS(on)}	漏极至源极静态导通电阻	V _{GS} = 10 V, I _D = 38 A	-	28	36	mΩ
9 _{FS}	正向跨导	V _{DS} = 20 V, I _D = 38 A	-	90	-	S

动态特性

C _{iss}	输入电容	V = 400 V V = 0V	-	9310	12385	pF
Coss	输出电容	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1 MHz	-	370	495	pF
C _{rss}	反向传输电容	1 171112	-\	3.1	5	pF
C _{oss}	输出电容	$V_{DS} = 380 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	- \	195	-	pF
C _{oss(eff.)}	有效输出电容	$V_{DS} = 0 \text{ V to } 380 \text{ V}, V_{GS} = 0 \text{ V}$	- 1	914	-	pF
Q _{g(tot)}	10V 的栅极电荷总量	V _{DS} = 380 V, I _D = 38 A,	-	218	285	nC
Q_{gs}	栅极 - 源极栅极电荷	V _{GS} = 10 V	-	39	-	nC
Q_{gd}	栅极 - 漏极 " 密勒 " 电荷	(说明 4)	-	66	-	nC
ESR	等效串联电阻 (G-S)	f = 1 MHz	-	1.0	-	Ω

开关特性

t _{d(on)}	导通延迟时间		-	34	78	ns
t _r	开通上升时间	$V_{DD} = 380 \text{ V}, I_D = 38 \text{ A},$	-/	24	58	ns
t _{d(off)}	关断延迟时间	$R_G = 25 \Omega$	-	235	480	ns
t _f	关断下降时间	(说明 4)	/ -	32	74	ns

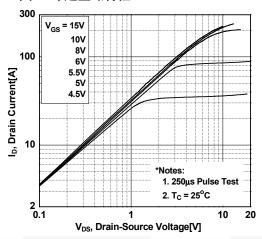
漏极 - 源极二极管特性

10119 100 1000 1						
I _S	漏极 - 源极二极管最大正向连续电流	漏极 - 源极二极管最大正向连续电流		-	76	Α
I_{SM}	漏极 - 源极二极管最大正向脉冲电流		-	-	228	Α
V_{SD}	漏极 - 源极二极管正向电压	$V_{GS} = 0 V, I_{SD} = 38 A$	-	-	1.2	V
t _{rr}	反向恢复时间	$V_{GS} = 0 \text{ V}, I_{SD} = 38 \text{ A},$	-	612	-	ns
Q_{rr}	反向恢复电荷	$dI_F/dt = 100 A/\mu s$	-	16	-	μC

- **注意:**1. 重复额定值: 脉冲宽度受限于最大结温。
- 2. I_{AS} = 25.3 A, R_G = 25 Ω ,启动 T_J = 25°C。
- $3.~I_{SD} \le 76~A,~di/dt \le 200~A/\mu s,~V_{DD} \le 380~V,~启动~T_J = 25^{\circ}C_{\circ}$
- 4. 本质上独立于工作温度的典型特性。

典型性能特征

图 1. 导通区域特性



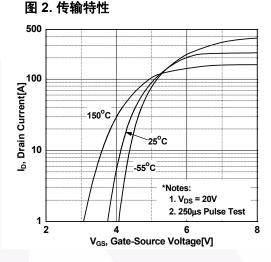


图 3. 导通电阻变化与漏极电流和栅极电压

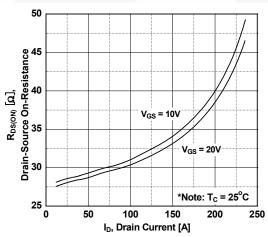


图 4. 体二极管正向电压变化与 源电流和温度

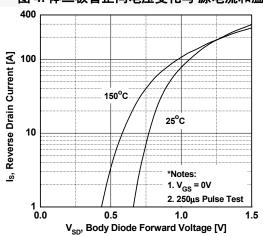


图 5. 电容特性

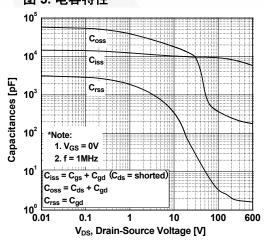
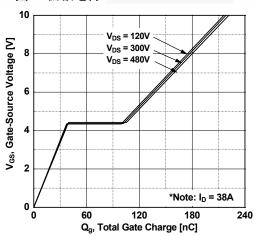


图 6. 栅极电荷



典型性能特征 (接上页)

图 7. 击穿电压变化与温度

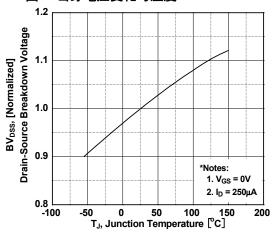


图 8. 导通电阻变化与温度

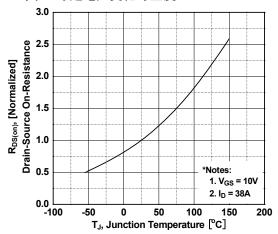


图 9. 最大安全工作区

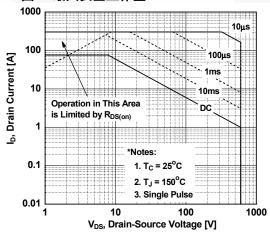


图 10. 最大漏极电流与壳体温度

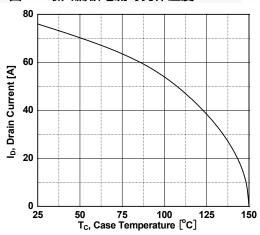
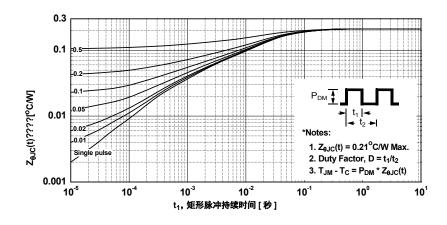


图 11. 瞬态热响应曲线



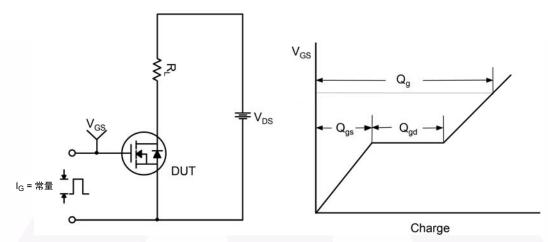


图 12. 栅极电荷测试电路与波形

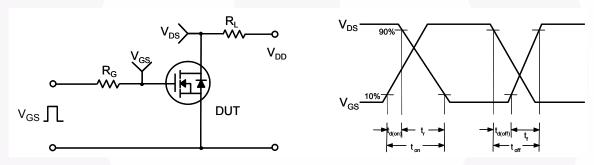


图 13. 阻性开关测试电路与波形

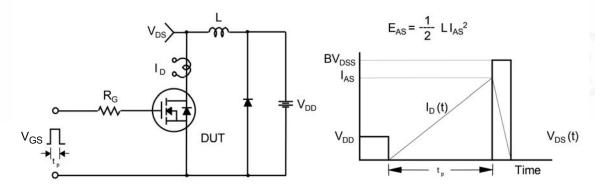


图 14. 非箝位感性开关测试电路与波形

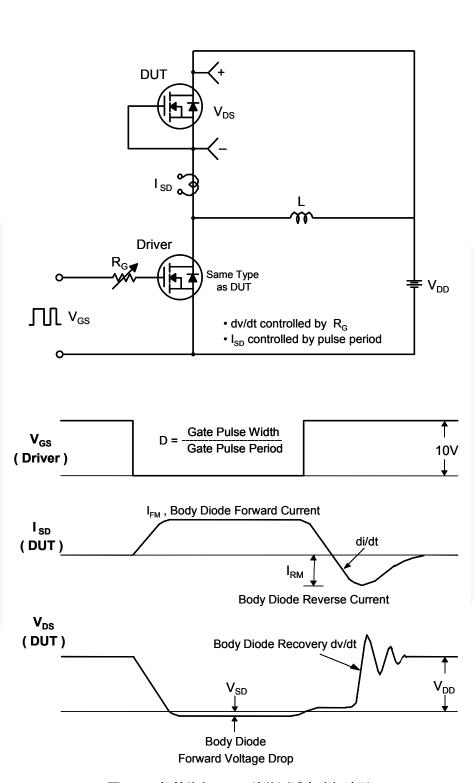
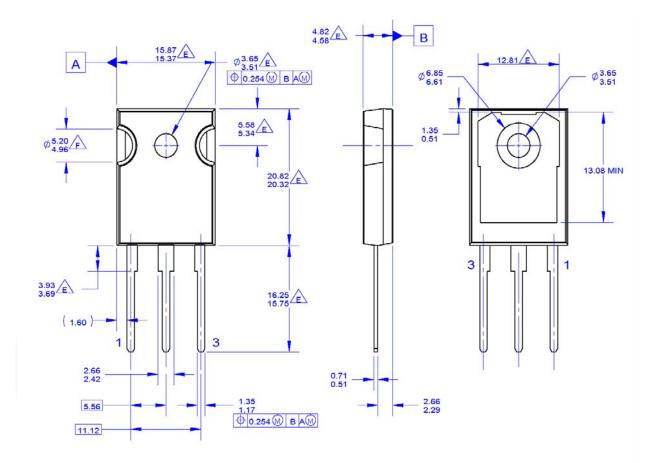


图 15. 二极管恢复 dv/dt 峰值测试电路与波形

机械尺寸



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G. DRAWING FILENAME: MKT-TO247A03_REV03

图 16. TO-247, 模塑, 3 引脚, Jedec Variation AB

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